Product Change Notification

The information below reflects a change that is being implemented.

Notice Date: 10/05/2007

Product Category: Linear Devices; Mixed Signal Devices; Power Management; Thermal Management; CAN Communication; Infrared Communication; LIN Communication; 24xxx; 25xxx; 93xxx; Other; PIC12xxx; PIC16xxx; PSxxx; RFID; SDP

Notification Subject: CCB#766.01 – 766.03: QUALIFICATION OF G700 TYPE MOLD COMPOUNDS IN TSSOP PACKAGES AT ATP

Notification Body:

All Microchip Catalog Part#s Affected For:
8L TSSOP assembled at ATP (CCB# 766.01 for G700A Mold Compound)
14L TSSOP assembled at ATP (CCB# 766.02 for G700K Mold Compound)
20L TSSOP assembled at ATP (CCB# 766.03 for G700K Mold Compound)

Description of Change:
CHANGE IN BOM

Impacts to Data Sheet:
NONE

Reason for Change:
CONVERSION TO G700 TYPE MOLD COMPOUNDS

Estimated Change Implementation Date(s):
OCTOBER 31, 2007

Markings to Distinguish Revised From Unrevised Devices:
(e.g.: Date Code, Device Marking, Ship Container Marking)

TRACEABILITY CODE